M705-RGS800HF Type 6

Features

- Sufficient solder quantity ensured by using Type 6 size fine powder
- Newly developed highly active flux facilitates removal of oxide film
- Uniquely developed flux suppresses reoxidation in reflow

Specifications

- Type 6 powder is necessary for land patterns for 0201-type chip components
  - Sufficient solder quantity cannot be obtained with large solder particle size

- Flux developed along with finer solder powder
  - Solder paste for 0201-type chip components

- Printing on a pattern with openings φ130µm in diameter and a mask 60 µm in thickness with various types of powders
  - Type 6 ensures sufficient printing

- Fusion defects are caused with a paste consisting of Type 6 powder and conventional flux
  - With Type 6 powder, the surface area and the oxide film area are doubled compared to Type 5 powder

- Ultra-high density mounting made possible by mounting of microscopic components
  - 0402-type component mounting
  - 0201-type component mounting

Component supplier: Murata Manufacturing Co., Ltd.